



Diode Module

Features

- A package of series of two diodes
- Heat transfer through alumina ceramic and metal substrate
- Welding by vacuum welding technology, which provide high reliability

Product Summary

Parameter	Value	Unit
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Applications

- AC converter
- Inverter
- DC motor

Absolute Maximum Ratings (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Conditions	Symbol	Values	Unit
Repetitive peak reverse voltage	$T_{vj} = 25^\circ\text{C}$	V_{RRM}	2000	V
Non-repetitive peak reverse voltage	$T_{vj} = 25^\circ\text{C}$	V_{RSM}	2100	V
Average forward current	$T_C = 100^\circ\text{C}$	$I_{F(AV)}$	250	A
Forward surge current	1/2 cycle, Sine wave, 50Hz	I_{FSM}	8000	A
I^2t value for fusing		I^2t	320000	A^2s
RMS isolation voltage	A.C 50Hz(1s/1min)	V_{ISO}	3600/3000	V
Junction temperature range		T_J	-40 ~ +150	
Storage temperature range		T_{stg}	-40 ~ +125	

**Electrical Characteristics (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)**

Parameter	Conditions	Symbol	Values			Unit
			Min.	Typ.	Max.	
Peak forward voltage	$I_F=750\text{A}$, $t_P=380$	V_{FM}			1.60	V
Reverse leakage current	$V_R = V_{RRM}$, $T_{vj} = 25^\circ\text{C}$	I_{RRM}			100	A
	$V_R = V_{RRM}$, $T_{vj} = 150^\circ\text{C}$				90	mA
Threshold voltage	$T_{vj} = 150^\circ\text{C}$, for power loss calculation only	V_{TO}			0.81	V
Dynamic resistance		r_T			0.8	$\text{m}\Omega$

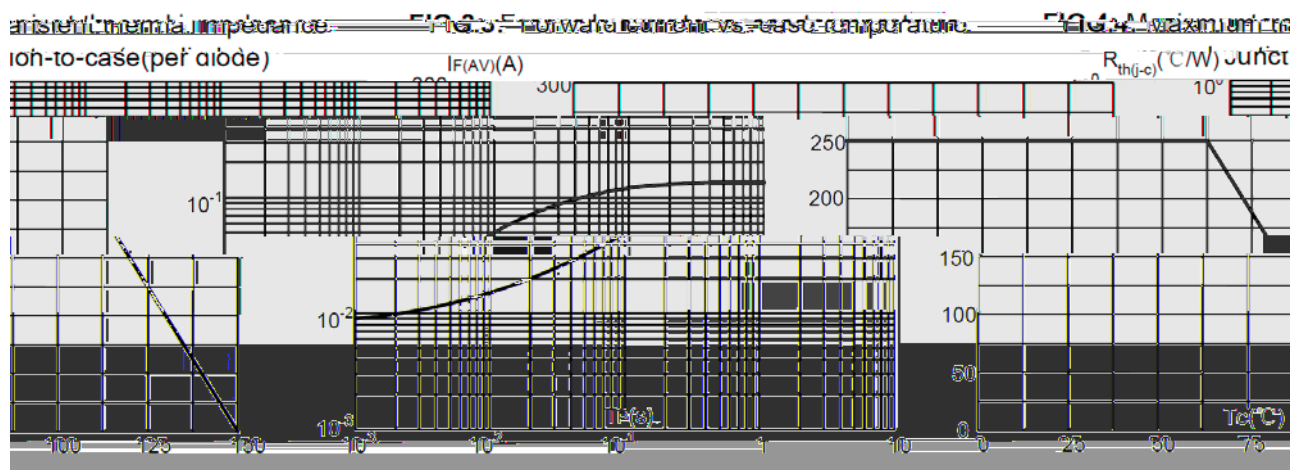
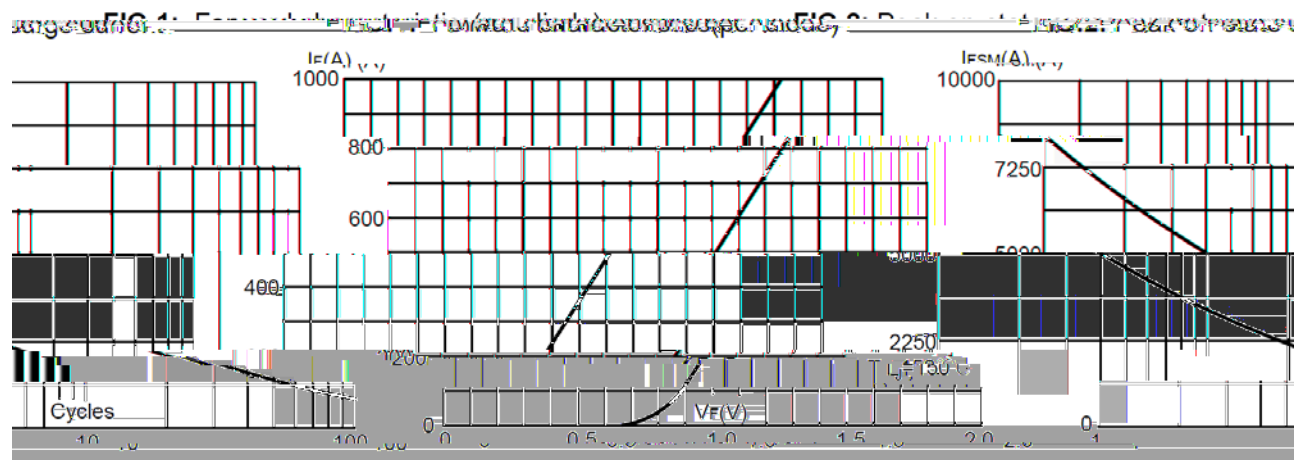
Thermal Characteristics (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Conditions	Symbol	Values			Unit
			Min.	Typ.	Max.	
Thermal resistance, junction to case	per diode	$R_{th(j-c)}$		0.13		/W
Thermal resistance, case to heatsink	per diode	$R_{th(c-s)}$		0.07		/W
Mounting torque	Module and heatsink fixed torque M5	M	4.25		5.75	N·m
	Electrode connection torque, screw M6		4.25		5.75	N·m

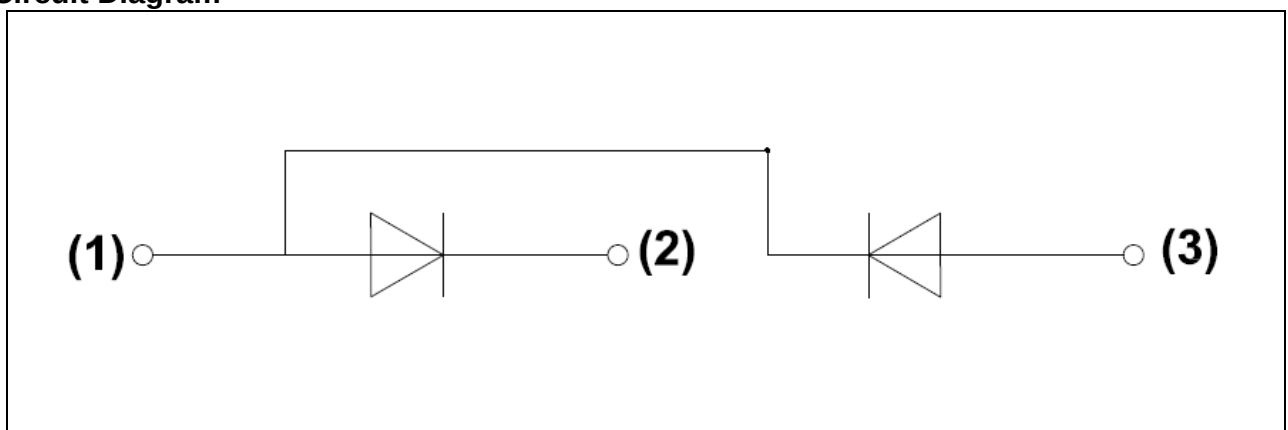
Ordering Information

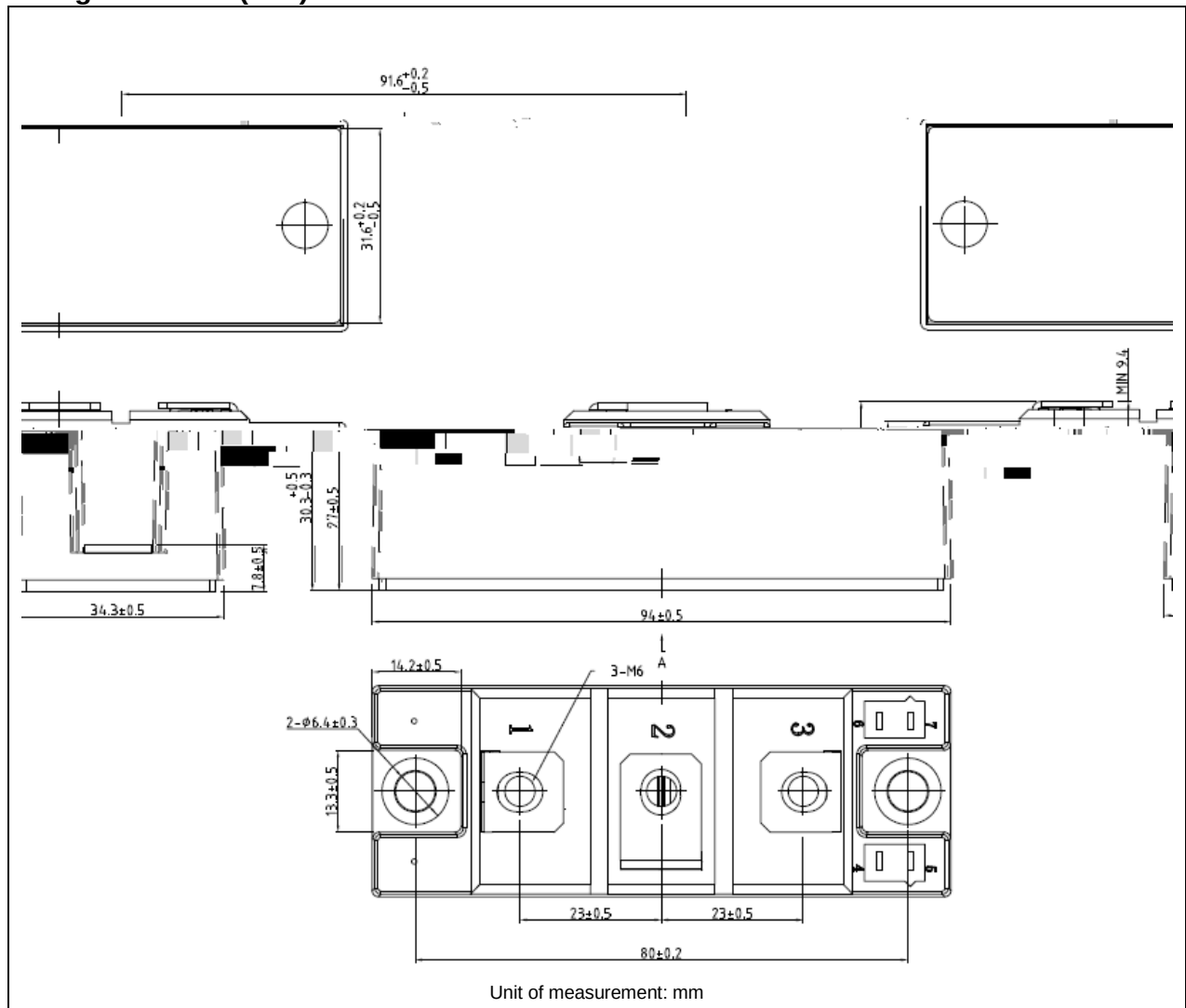
Device	Marking	Package	Weight	Inner Box	Pre Carton
JMD250KD20T2W	JMD250KD20T2W	T2	170 10g/PCS	6 PCS	72 PCS

Typical Electrical & Thermal Characteristics



Circuit Diagram



Package Outlines (mm)




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